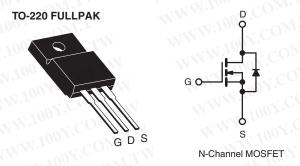


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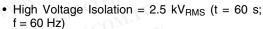
Power MOSFET

| PRODUCT SUMMARY | | | | | |
|----------------------------|------------------------|-------|--|--|--|
| V _{DS} (V) | 60 | | | | |
| R _{DS(on)} (Ω) | V _{GS} = 10 V | 0.050 | | | |
| Q _g (Max.) (nC) | 46 | | | | |
| Q _{gs} (nC) | NW 10011 | | | | |
| Q _{gd} (nC) | 22 | | | | |
| Configuration | Single | | | | |



FEATURES

Isolated Package





- Sink to Lead Creepage Distance = 4.8 mm
- 175 °C Operating Temperature
- · Dynamic dV/dt Rating
- Low Thermal Resistance
- Lead (Pb)-free Available

DESCRIPTION

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220 FULLPAK eliminates the need for additional insulating hardware in commercial-industrial applications. The molding compound used provides a high isolation capability and a low thermal resistance between the tab and external heatsink. The isolation is equivalent to using a 100 micron mica barrier with standard TO-220 product. The FULLPAK is mounted to a heatsink using a single clip or by a single screw fixing.

| ORDERING INFORMATION | M. rank Comment |
|-----------------------|-----------------|
| Package | TO-220 FULLPAK |
| Lead (Pb)-free | IRFIZ34GPbF |
| | SiHFIZ34G-E3 |
| SnPb WWW.LIMBY.COMW W | IRFIZ34G |
| | SiHFIZ34G |

| PARAMETER | | N 7 C | SYMBOL | LIMIT | UNIT | |
|--|---------------------------------------|-------------------------|-----------------------------------|------------------|-----------|--|
| Drain-Source Voltage | - W.I.M. W. 100x. | | | 60 | | |
| Gate-Source Voltage | 7. T.W. W.W. 1002.1 | | | ± 20 | V | |
| Continuous Drain Current | V _{GS} at 10 V | T _C = 25 °C | V _{GS} | 20 | N.C. | |
| | | T _C = 100 °C | COID | 14 | (A) | |
| Pulsed Drain Currenta | | | I _{DM} | 80 | -1 CC | |
| Linear Derating Factor | | | TIME | 0.28 | W/°C | |
| Single Pulse Avalanche Energy ^b | e Pulse Avalanche Energy ^b | | | 300 | mJ | |
| Maximum Power Dissipation | T _C = 25 °C | | PD | 42 | W | |
| Peak Diode Recovery dV/dtc | V/dt ^c | | dV/dt | 5.0 | V/ns | |
| Operating Junction and Storage Temperature Range | | | T _J , T _{stg} | - 55 to + 175 | °C | |
| Soldering Recommendations (Peak Temperature) | for 10 s | | · LOW | 300 ^d | 1 W. P.C. | |
| Mounting Toyaus | 6.20.0* | 0.00 140 | | 10 | lbf ⋅ in | |
| Mounting Torque | 6-32 or M3 screw | | 1001.0 | 1.1 V | N · m | |

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
b. V_{DD} = 25 V, starting T_J = 25 °C, L = 875 µH R_O = 25 Q A (see fig. 12). WWW.100Y.COM.TW

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- c. $I_{SD} \leq 30$ A, $dI/dt \leq 200$ A/ μs , $V_{DD} \leq V_{DS}$, $T_J \leq 175$ °C.

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply



| VISITALY SHICOTHX | COM.TW | MMM.100X.C | COW.TW | | |
|----------------------------------|-------------------|------------|--------|------|--|
| THERMAL RESISTANCE RA | ATINGS | MAM. Too | V.COM. | | |
| PARAMETER | SYMBOL | TYP. | MAX. | UNIT | |
| Maximum Junction-to-Ambient | R _{thJA} | W. 10 | 65 | °C/W | |
| Maximum Junction-to-Case (Drain) | R _{thJC} | -WW | 3.6 | | |

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| PARAMETER | SYMBOL | TES | MIN. | TYP. | MAX. | UNIT | |
|---|-----------------------|---|-------------|------------|------------------------|------------------|------|
| Static | 1.100 r. | $W_{1,1}$ | MAN Jan | M. | (X) | | |
| Drain-Source Breakdown Voltage | V _{DS} | $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$ | | 60 | <u>-</u> | - | V |
| V _{DS} Temperature Coefficient | $\Delta V_{DS}/T_{J}$ | Reference to 25 °C, I _D = 1 mA | | Wo. | 0.065 | - | V/°C |
| Gate-Source Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$ | | 2.0 | TV | 4.0 | V |
| Gate-Source Leakage | I _{GSS} | V _{GS} = ± 20 V | | Con | With | ± 100 | nA |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} = 60 V, V _{GS} = 0 V V _{DS} = 48 V, V _{GS} = 0 V, T _J = 150 °C | | 4.GO | TW | 25 | μΑ |
| 2010 date Voltage Brain Guilent | DSS | | | ST-CC | Mr. | 250 | μΛ |
| Drain-Source On-State Resistance | R _{DS(on)} | V _{GS} = 10 V I _D = 12 A ^b | | 10 x | DNT: T | 0.050 | Ω |
| Forward Transconductance | 9 _{fs} | $V_{DS} = 25 \text{ V}, I_D = 12 \text{ A}^b$ | | 9.2 | LIVO | | S |
| Dynamic | MMM | TOON COL | IN MAL | 1001 | | TW | |
| Input Capacitance | C _{iss} | $V_{GS} = 0 \text{ V},$ $V_{DS} = 25 \text{ V},$ f = 1.0 MHz, see fig. 5 | | 4007 | 1200 | WT | - pF |
| Output Capacitance | C _{oss} | | | N. 1- | 600 | W | |
| Reverse Transfer Capacitance | C _{rss} | | | 11.700 | 100 | M. | |
| Drain to Sink Capacitance | С | W.1001. | f = 1.0 MHz | W.10 | 12 | | . SI |
| Total Gate Charge | Q_g | W.100Y.C | WI.Mo. | - N. | 00 F. | 46 | |
| Gate-Source Charge | Q _{gs} | $V_{GS} = 10 \text{ V}$ $I_D = 30 \text{ A}, V_{DS} = 48 \text{ V}$ see fig. 6 and 13 ^b | | 100x. | 11/ | nC | |
| Gate-Drain Charge | Q _{gd} | See lig. 6 dila 16 | | MAI | 1.100X | | 22 |
| Turn-On Delay Time | t _{d(on)} | WW 100 | A'CO, TA | Min | 13 | | T.M |
| Rise Time | t _r | V_{DD} = 30 V, I_{D} = 30 A R_{G} = 12 Ω, R_{D} = 1.0 Ω, see fig. 10 ^b | | 4 W | 100 | Y.C. | ns |
| Turn-Off Delay Time | t _{d(off)} | | | -1/1 | 29 | WY-C | |
| Fall Time | t _f | | | - 11 | 52 | V.C | |
| Internal Drain Inductance | L _D | Between lead, 6 mm (0.25") from package and center of die contact | | - | 4.5 | 100X | nH |
| Internal Source Inductance | L _S | | | - | 7.5 | N.100 | |
| Drain-Source Body Diode Characteristic | es M.T. | | MAIN TOWN | * 1 | | Min | ×1 (|
| Continuous Source-Drain Diode Current | v.cds I.T. | MOSFET symbol showing the integral reverse p - n junction diode | | W - | -11 | 20 | 00A |
| Pulsed Diode Forward Current ^a | I _{SM} | | | TW | - 1 | 80 | |
| Body Diode Voltage | V _{SD} | $T_J = 25 ^{\circ}\text{C}, I_S = 20 \text{A}, V_{GS} = 0 \text{V}^b$ | | 1.1. | - | 1.6 | V |
| Body Diode Reverse Recovery Time | t _{rr} | $T_J = 25 ^{\circ}\text{C}$, $I_F = 30 \text{A}$, $dI/dt = 100 \text{A/}\mu\text{s}^b$ | | M.TW | 120 | 230 | ns |
| Body Diode Reverse Recovery Charge | Q _{rr} | | | TT | 0.70 | 1.4 | μC |
| Forward Turn-On Time | t _{on} | Intrinsic tu | on is dor | minated by | y L _S and I | L _D) | |

Notes

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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

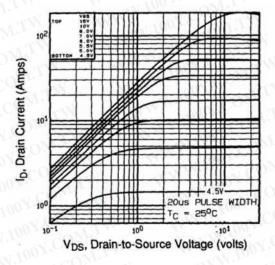


Fig. 1 - Typical Output Characteristics, T_C = 25 °C

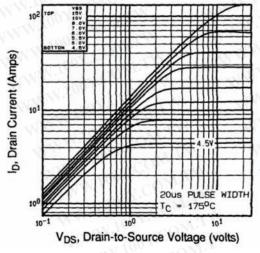


Fig. 2 - Typical Output Characteristics, T_C = 175 °C

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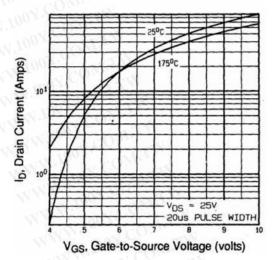
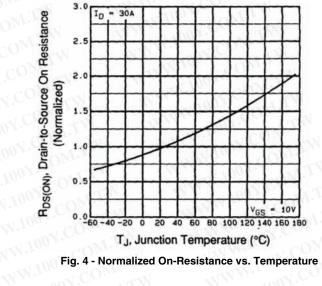


Fig. 3 - Typical Transfer Characteristics





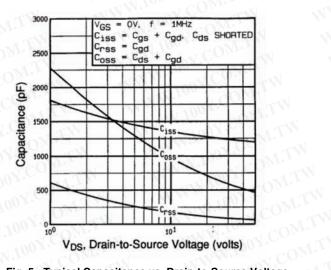
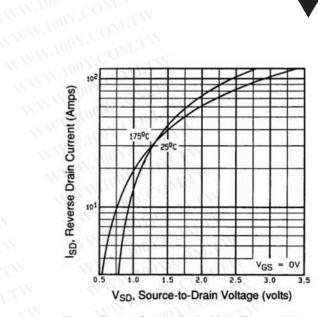


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage



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Fig. 7 - Typical Source-Drain Diode Forward Voltage

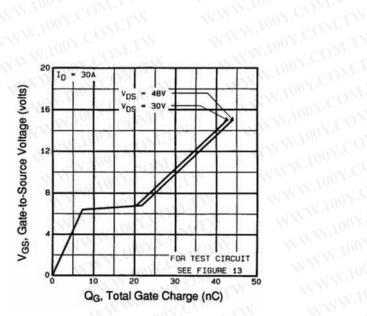
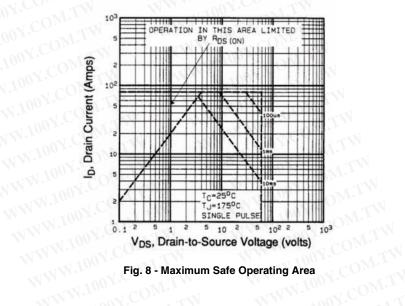
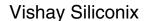


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

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WWW.100Y.COM.TW Fig. 8 - Maximum Safe Operating Area





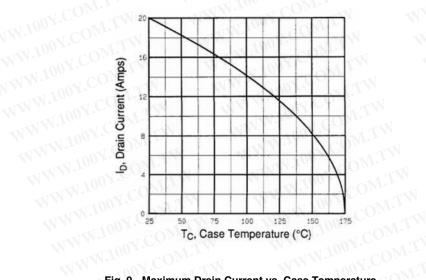


Fig. 9 - Maximum Drain Current vs. Case Temperature WWW.1007

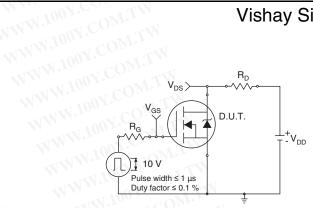


Fig. 10a - Switching Time Test Circuit

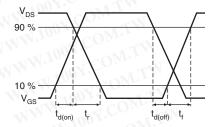


Fig. 10b - Switching Time Waveforms

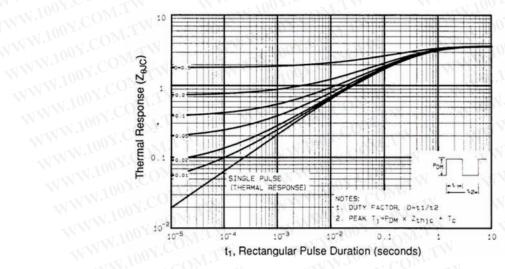


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case WWW.100Y.C

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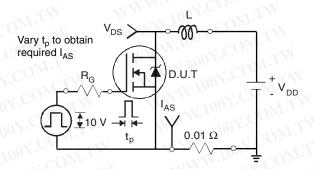


Fig. 12a - Unclamped Inductive Test Circuit

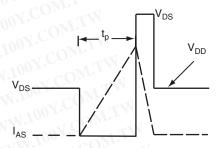
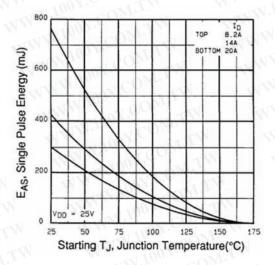


Fig. 12b - Unclamped Inductive Waveforms



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Fig. 12c - Maximum Avalanche Energy vs. Drain Current

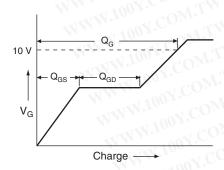


Fig. 13a - Basic Gate Charge Waveform

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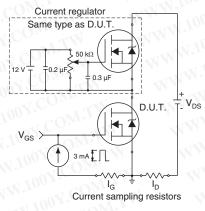
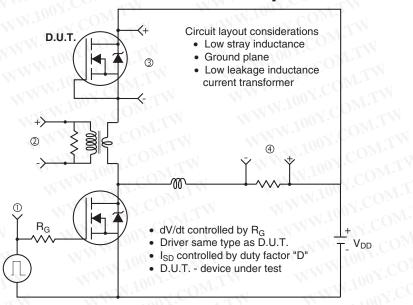


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



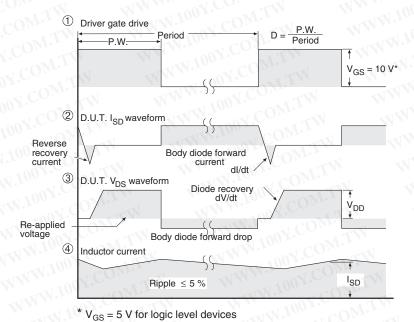


Fig. 14 - For N-Channel

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